

VOLTAGE REGULATOR WITH ON/OFF SWITCH

FEATURES

- Low Dropout Voltage
- Electronic ON/OFF Switch
- Very Low Standby Current (ON, No Load)
- Internal Thermal Shutdown
- Short Circuit Protection
- Very Low (<100 nA) Current in OFF Mode
- 100 mA Load Capability
- Customized Versions Are Available

APPLICATIONS

- Battery Powered Systems
- Cellular Telephones
- Pagers
- Personal Communications Equipment
- Portable Instrumentation
- Portable Consumer Equipment
- Radio Control Systems
- Toys
- Low Voltage Systems

DESCRIPTION

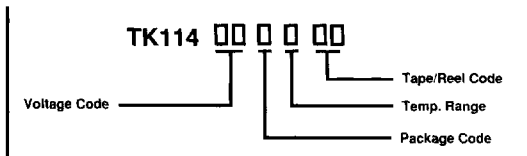
The TK114xx is a low power, linear regulator with a built-in electronic switch. The internal electronic switch can be controlled by an external pull-up resistor and an open drain or open collector transistor. The device is in the OFF state when the control pin is biased from V_{IN} through the pull-up resistor.

An internal PNP pass-transistor is used in order to achieve low dropout voltage (typically 200 mV at 50 mA load current). The device has very low quiescent current (500 μ A) in the ON mode with no load and 2 mA with 30 mA load. The quiescent current is typically 4 mA at 60 mA load. An internal thermal shutdown circuit limits the junction temperature to below 150 °C. The load current is internally monitored and the device will shut down (no load current) in the presence of a short circuit at the output. The regulated output voltage may be specified in 0.5 V increments between 2.0 to 5.5 V. Additionally, 3.25 V, 6.0 V and 8.0 V versions are also available. Separate data sheets are provided for the various options.

The device is available in a plastic SOT-23L package. Tape and reel mounted devices are also available.

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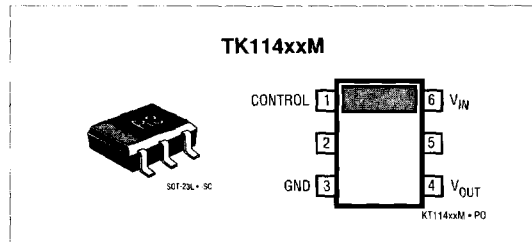
ORDERING INFORMATION



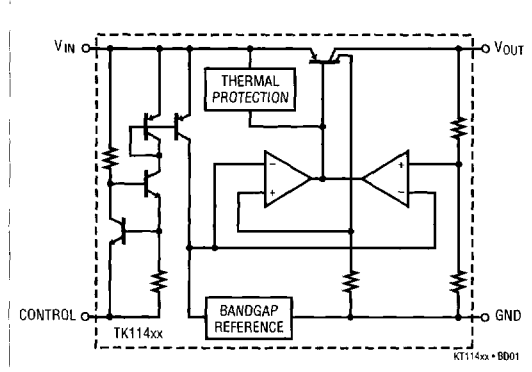
VOLTAGE CODE	
20 = 2.0 V	40 = 4.0 V
25 = 2.5 V	45 = 4.5 V
30 = 3.0 V	50 = 5.0 V
32 = 3.25 V	60 = 6.0 V
35 = 3.5 V	80 = 8.0 V

PACKAGE CODE	
M	Surface Mount
TEMP. RANGE	
C	-20 - 70 °C
I	-40 - 85 °C

TAPE/REEL CODE	
BX	Bulk/Bag
TX	Paper Tape
TR	Tape Right
TL	Tape Left



BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Supply Voltage 14 V
 Output Voltage $V_{OUT} \times 1.15$ V
 Load Current 180 mA
 Power Dissipation (Note 1) 200 mW

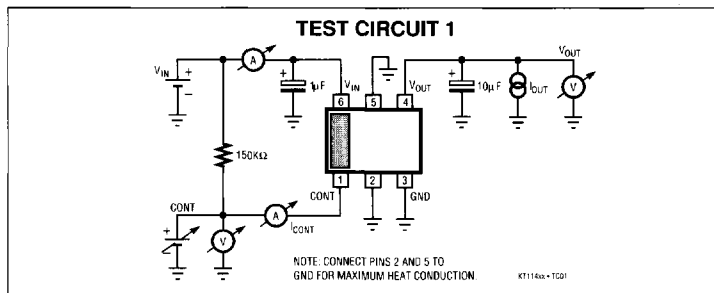
Storage Temperature Range -55 to +150 °C
 Operating Temperature Range (I Version) -40 to +85 °C
 Operating Temperature Range (C Version) -20 to +70 °C
 Lead Soldering Temp. (10 sec.) 240 °C
 Junction Temperature 150 °C

ELECTRICAL CHARACTERISTICS

Due to the common format used here, some specifications may not apply to all versions of output voltages. Detailed specifications are available for each version.

SYMBOL	PARAMETER	TEST CONDITION	-20 to +70 °C			-40 to +85 °C			UNITS
			MIN	TYP	MAX	MIN	TYP	MAX	
V_{IN}	Supply Voltage Range		2.5		14	2.5		14	V
I_{IN1}	Supply Current 1	$V_{IN} = V_O + 1$ V, $I_O = 0$ mA		500	900		500	900	µA
I_{IN2}	Supply Current 2	$V_{IN} = V_O - (1$ V to 0.1 V), $I_O = 0$ mA		1.0	2.5		1.0	2.5	mA
I_{IN3}	Supply Current 3	$V_{IN} = 10$ V, $V_{OUT} =$ Off mode		0.1	2		0.1	3	mA
V_O	Regulated Output Voltage	$V_{IN} = V_O + 1$ V, $I_O = 30$ mA, $T_A = 25$	±3.5% or ±100						mV
V_O	Regulated Output Voltage	$V_{IN} = V_O + 1$ V, $I_O = 30$ mA	±4.5% or 130			±5% or 140			mV
V_{DROP1}	Dropout Voltage 1	$I_O = 30$ mA		0.12	0.3		0.12	0.3	V
I_O	Output Current			110			100		mA
I_{OR}	Recommended Output Current				70			70	mA
LI_{REG}	Line Regulation	$V_{OUT} + 1$ V ≤ V_{IN} ≤ $V_{OUT} + 6$ V		2	20		2	20	mV
LD_{REG}	Load Regulation	$V_{IN} = V_O + 1$ V, $I_O = 0$ to 60 mA		35	110		35	110	mV
I_{CONT}	Control Pin Current			35	120		35	120	µA
V_{Coff}	Control Pin Voltage	Off Mode	$V_{IN} - 0.2$		V_{IN}	$V_{IN} - 0.2$		V_{IN}	V
V_{Con}	Control Pin Voltage	On Mode	0		$V_{IN} - 1.0$	0		$V_{IN} - 1.0$	V
RR	Ripple Rejection	100 mV(rms), $f = 400$ Hz $V_{IN} = V_O + 1.5$ V, $I_O = 10$ mA		55			55		dB
$\Delta V/\Delta T$	V_O Temperature Coefficient	$V_{IN} = V_O + 1.5$ V, $I_O = 10$ mA		0.6			0.6		mV/°C
V_N	Output Noise Voltage	$V_{IN} = V_O + 1.5$ V, $I_O = 10$ mA $C_L = 10$ µF		180			180		µV(rms)

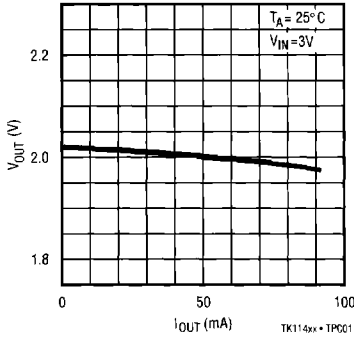
Note 1: Power dissipation must be derated at the rate of 1.6 mW/°C for operation at $T_A = 25$ °C and above. Power dissipation = 400 mW when mounted as recommended.



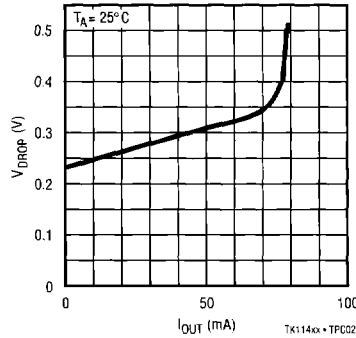
TYPICAL PERFORMANCE CHARACTERISTICS

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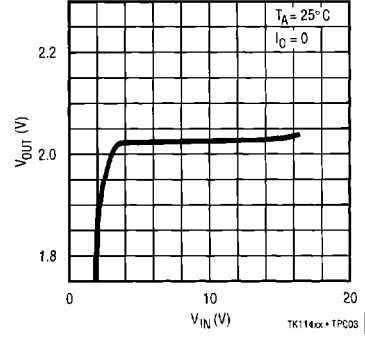
OUTPUT VOLTAGE vs
OUTPUT CURRENT



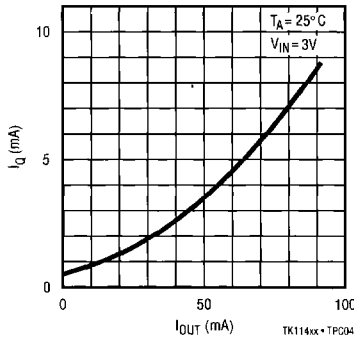
DROPOUT VOLTAGE vs
LOAD CURRENT



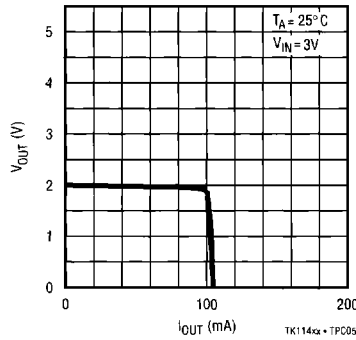
OUTPUT VOLTAGE vs
INPUT VOLTAGE



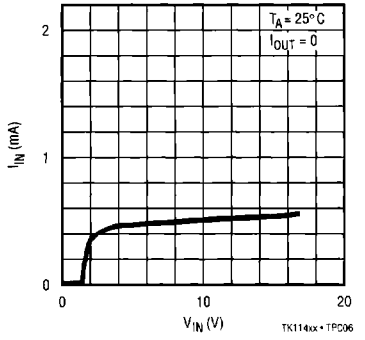
QUIESCENT CURRENT vs
LOAD CURRENT



SHORT CIRCUIT
PROTECTION



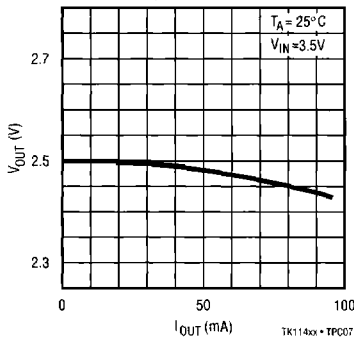
INPUT CURRENT vs
INPUT VOLTAGE



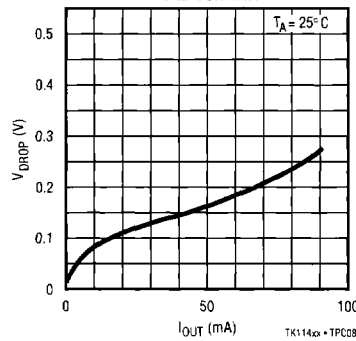
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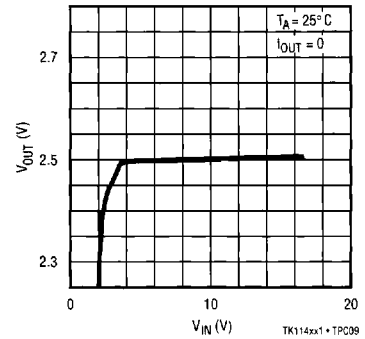
OUTPUT VOLTAGE vs
OUTPUT CURRENT



DROPOUT VOLTAGE vs
LOAD CURRENT



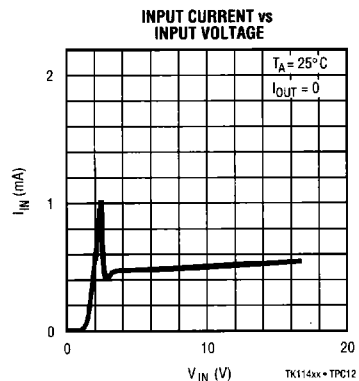
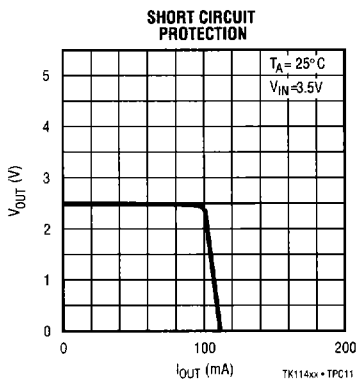
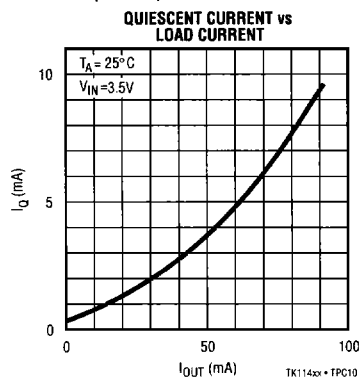
OUTPUT VOLTAGE vs
INPUT VOLTAGE



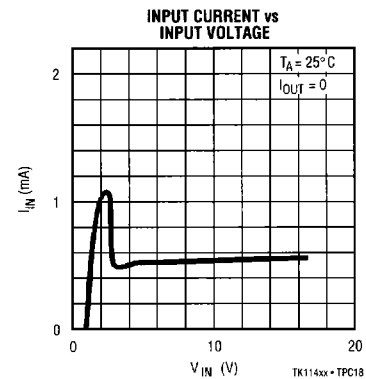
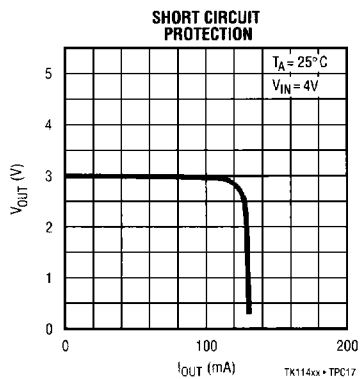
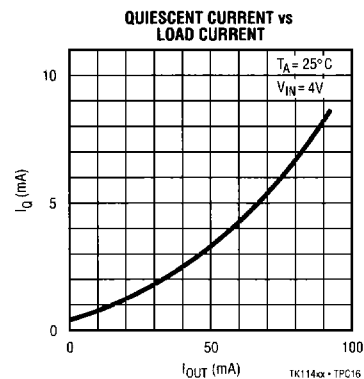
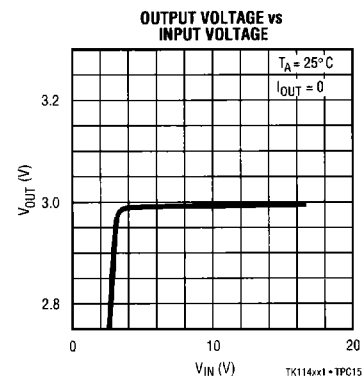
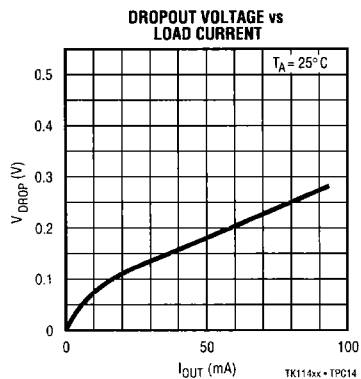
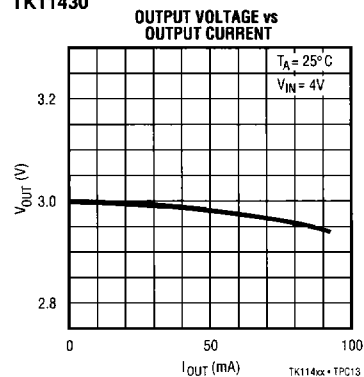
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TYPICAL PERFORMANCE CHARACTERISTICS (CONT.)

TK11425 (CONT.)

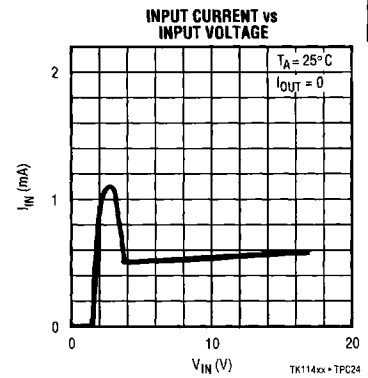
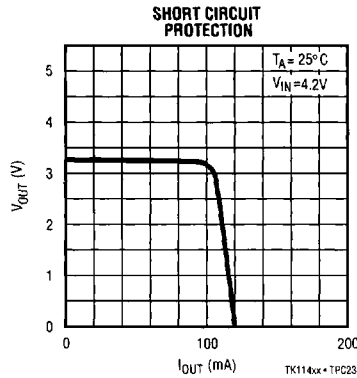
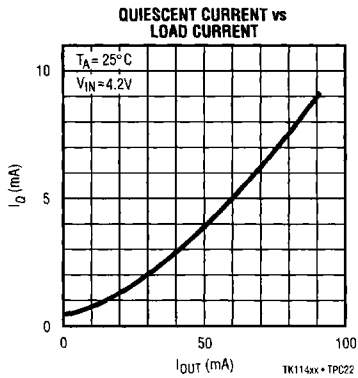
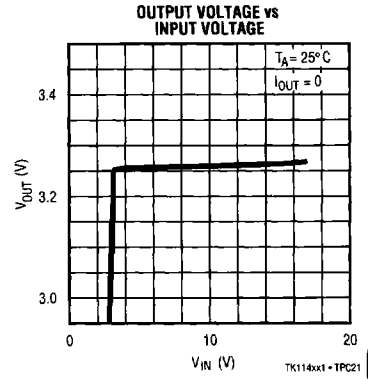
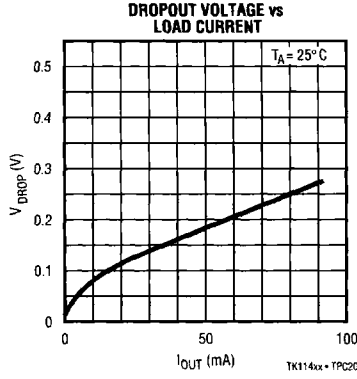
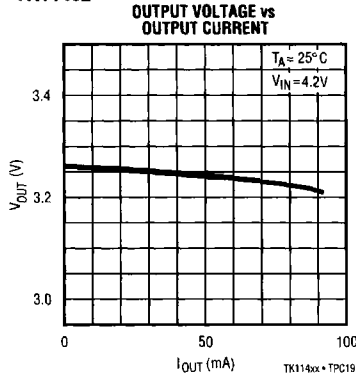


TK11430



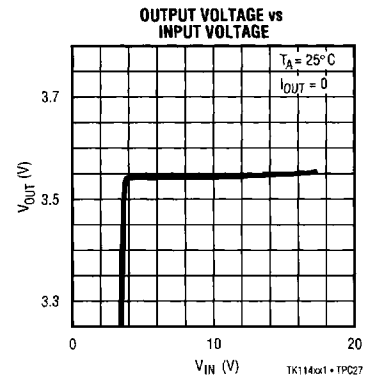
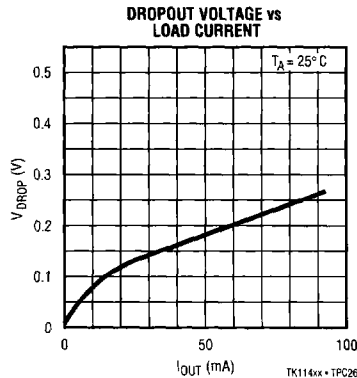
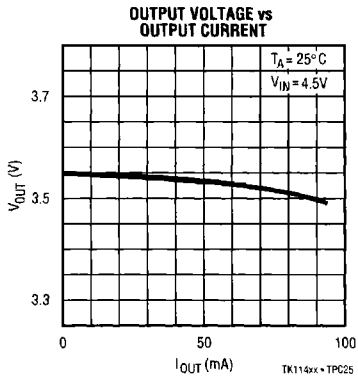
TYPICAL PERFORMANCE CHARACTERISTICS (CONT.)

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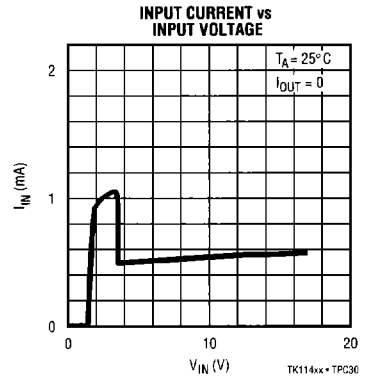
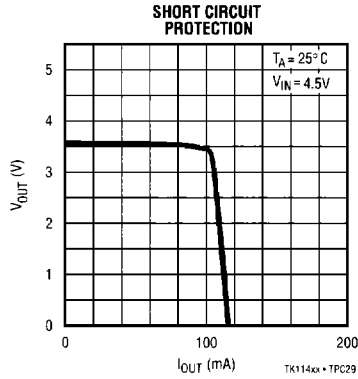
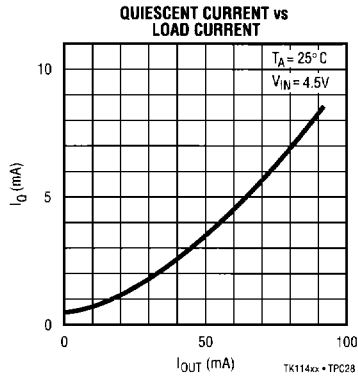
TK11435



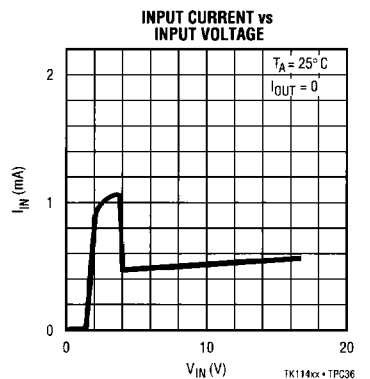
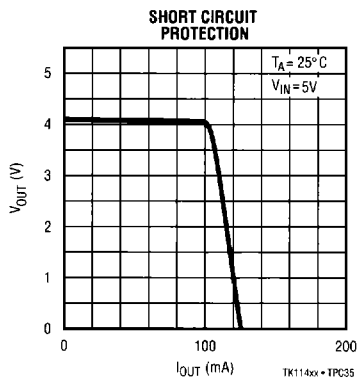
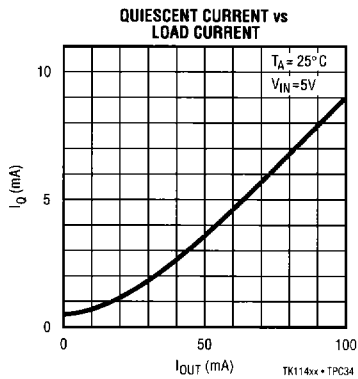
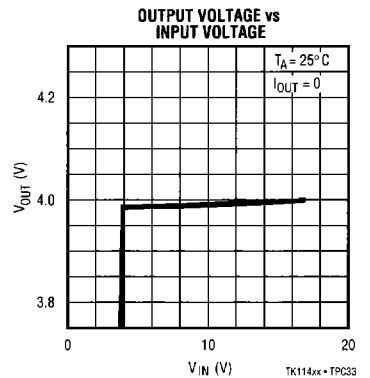
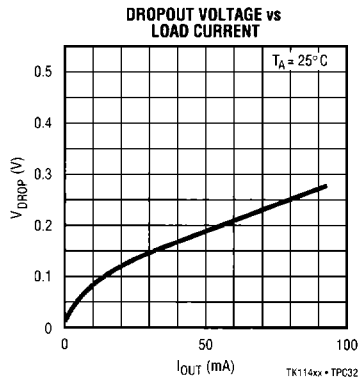
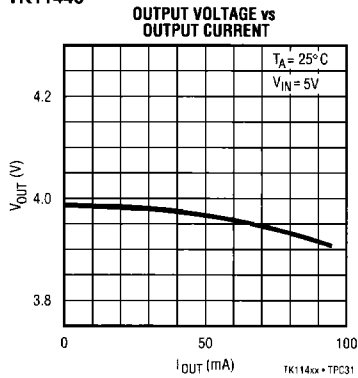
TK114xx

TYPICAL PERFORMANCE CHARACTERISTICS (CONT.)

TK11435 (CONT.)

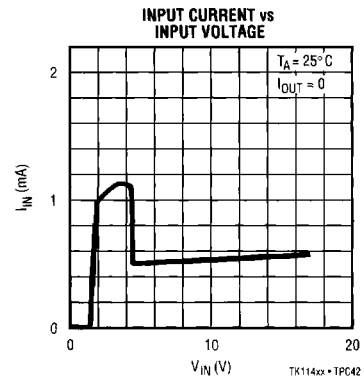
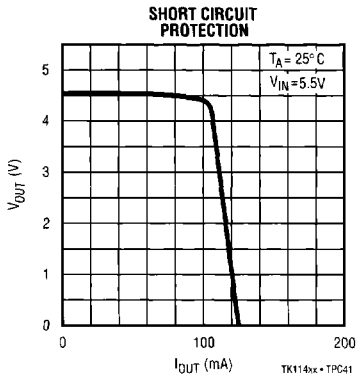
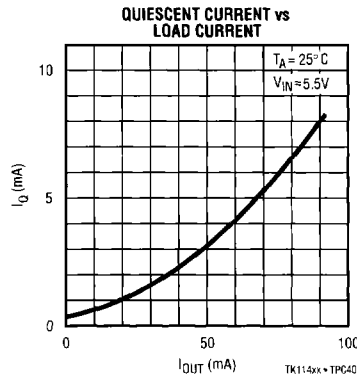
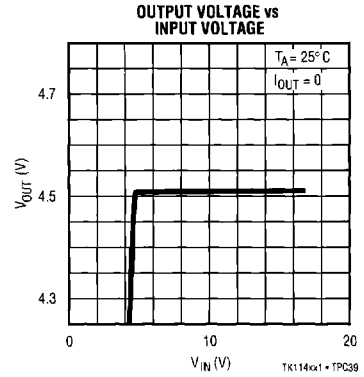
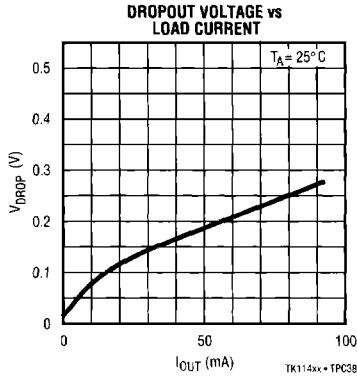
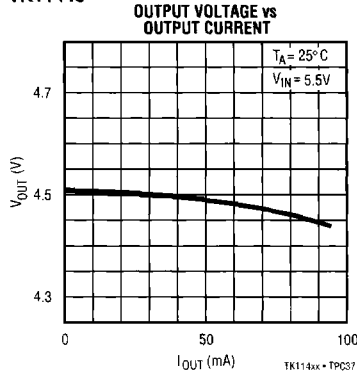


TK11440

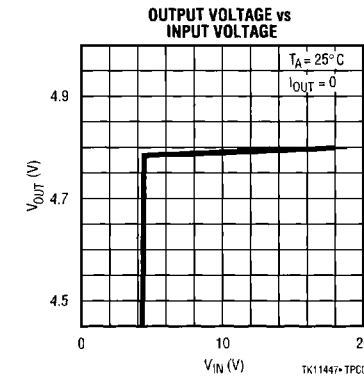
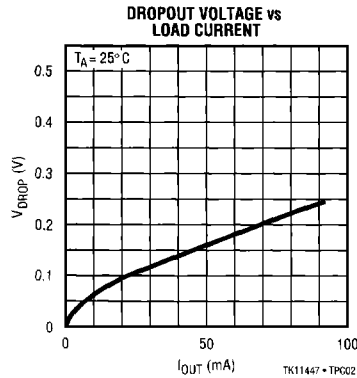
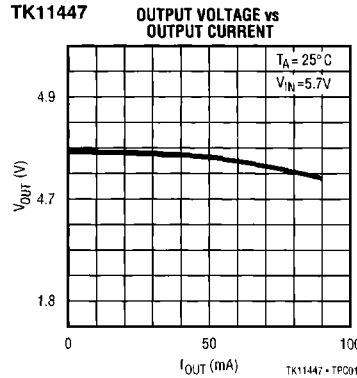


TYPICAL PERFORMANCE CHARACTERISTICS (CONT.)

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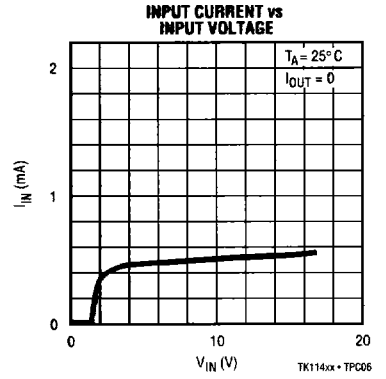
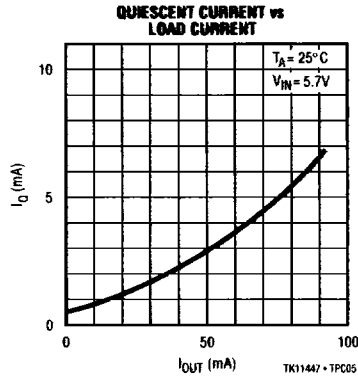
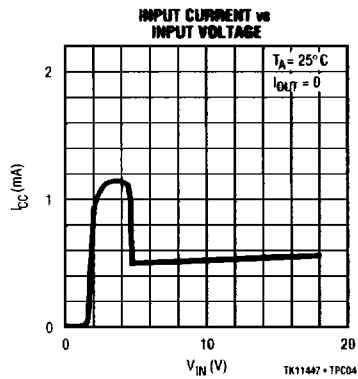


3

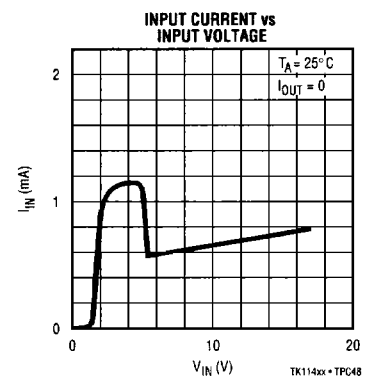
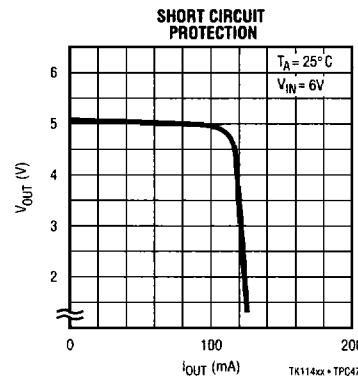
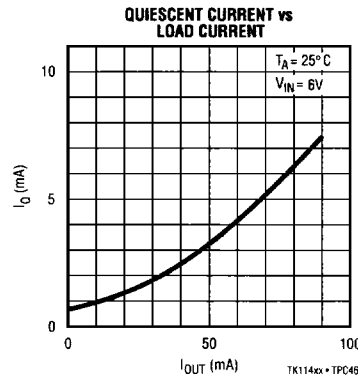
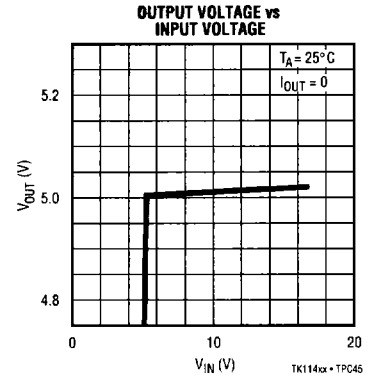
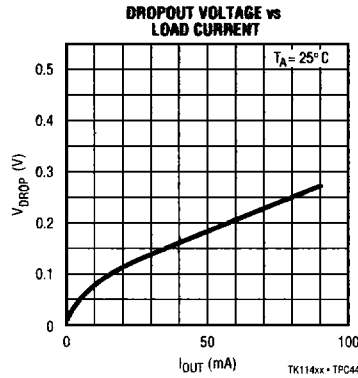
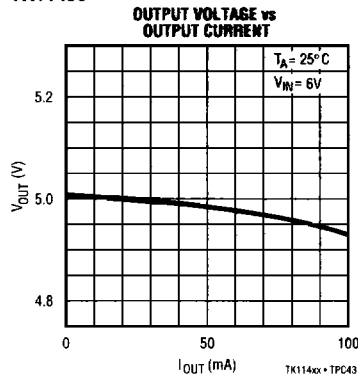
TK114xx

TYPICAL PERFORMANCE CHARACTERISTICS (CONT.)

TK11447 (CONT.)

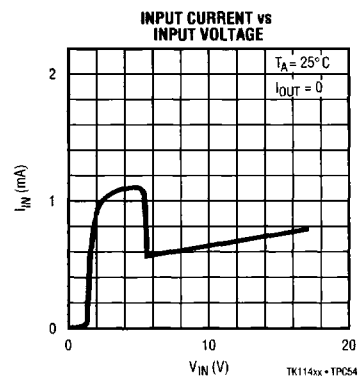
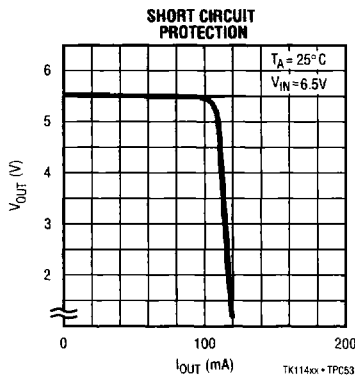
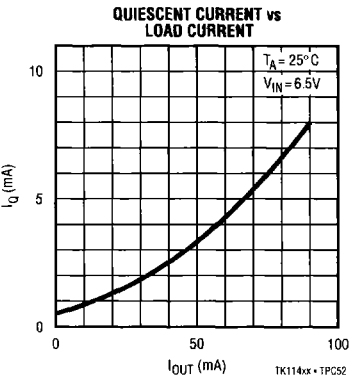
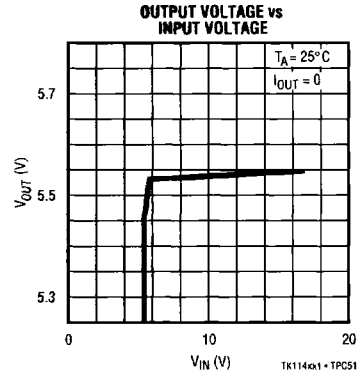
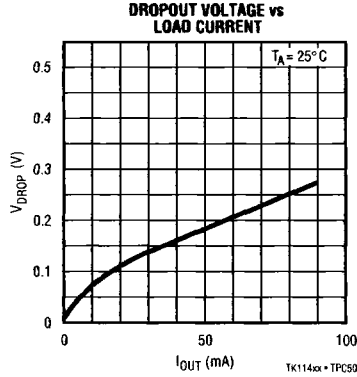
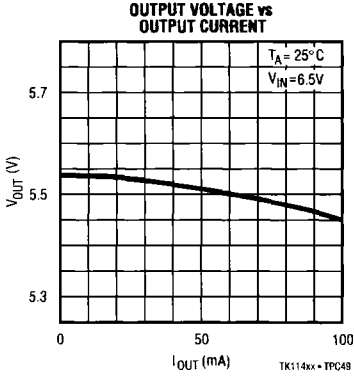


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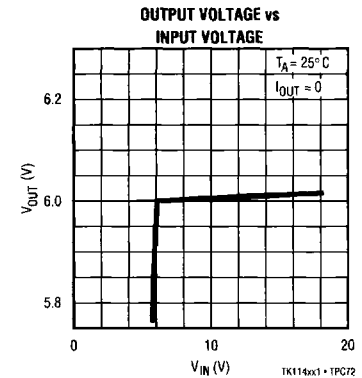
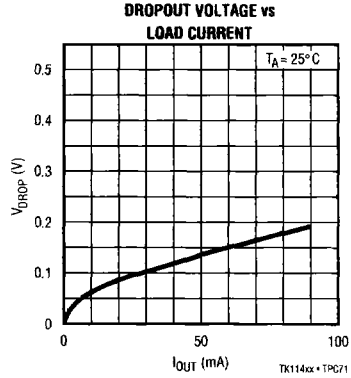
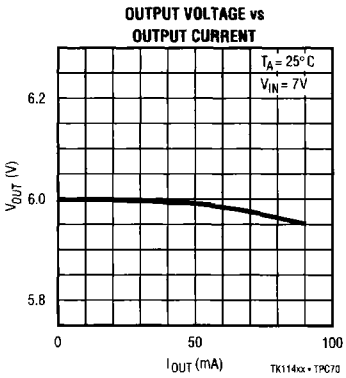
TYPICAL PERFORMANCE CHARACTERISTICS (CONT.)

TK11455



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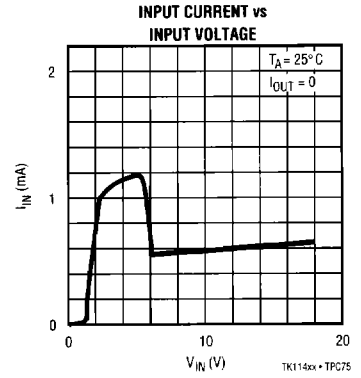
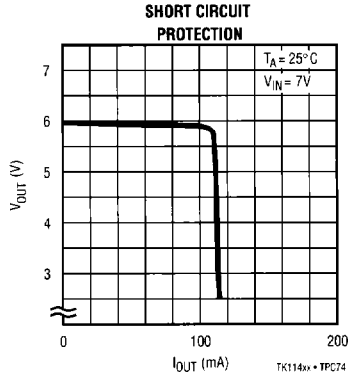
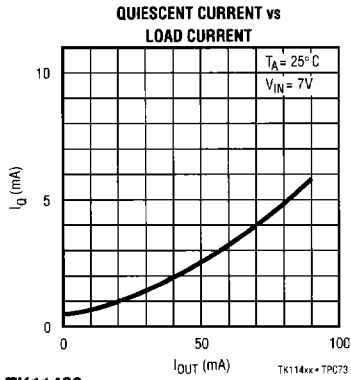
TK11460



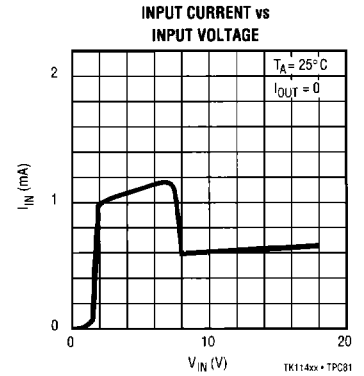
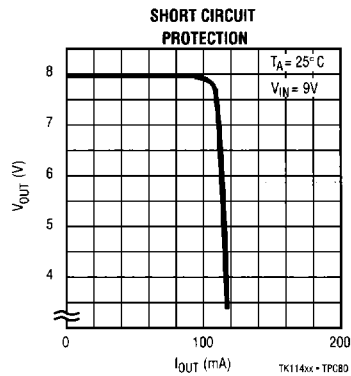
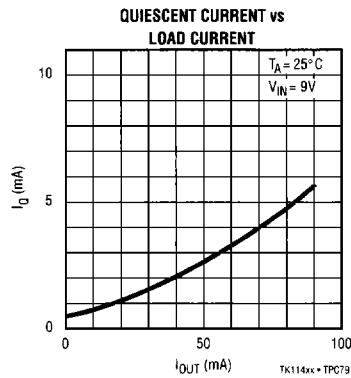
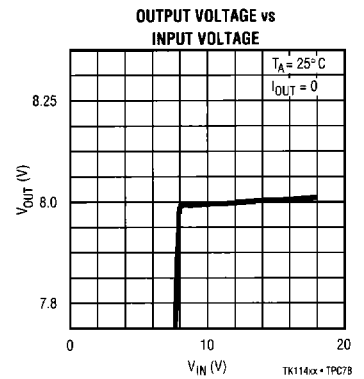
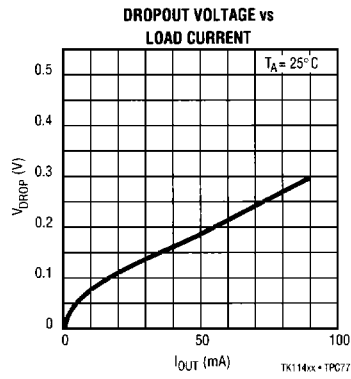
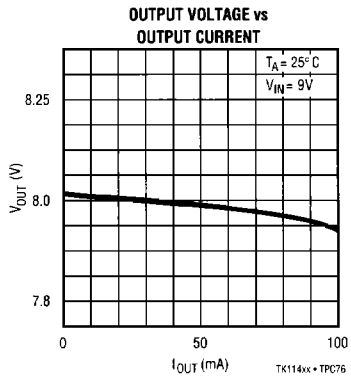
TK114xx

TYPICAL PERFORMANCE CHARACTERISTICS (CONT.)

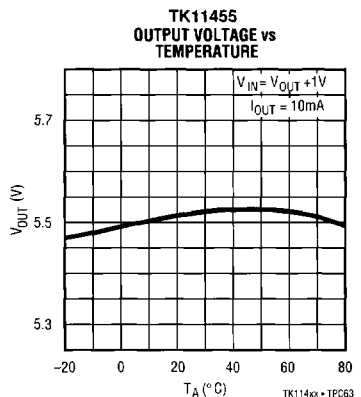
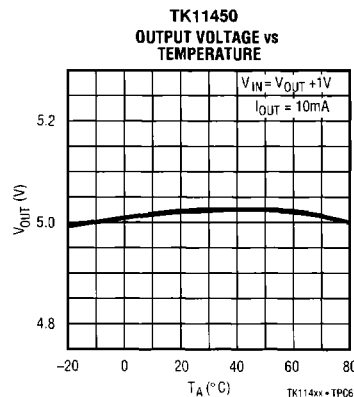
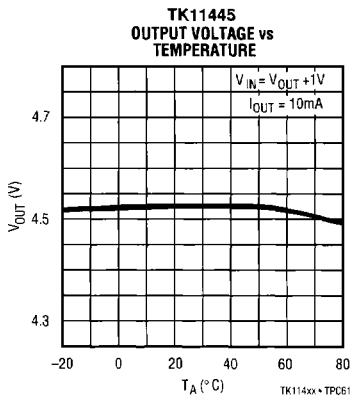
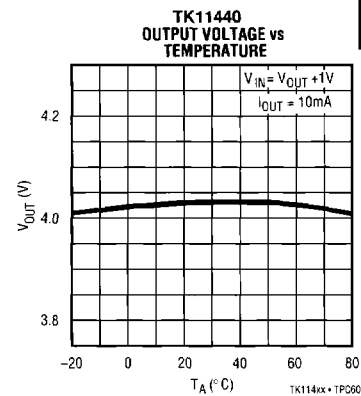
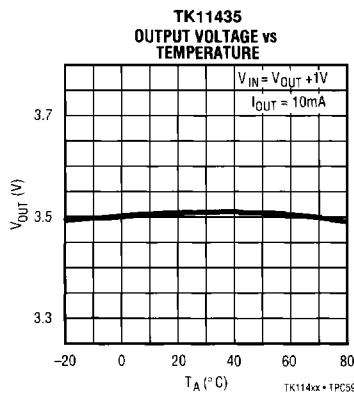
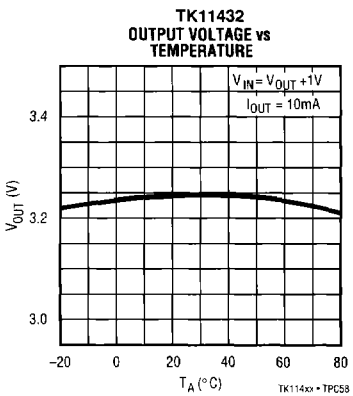
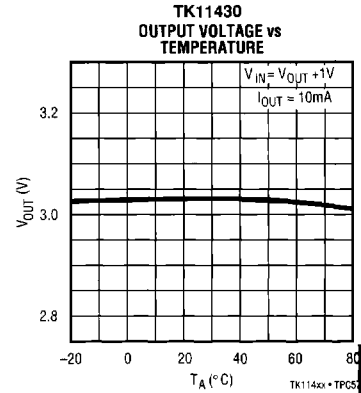
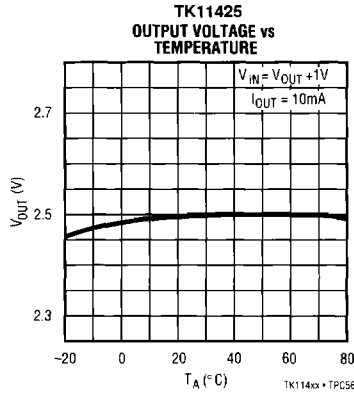
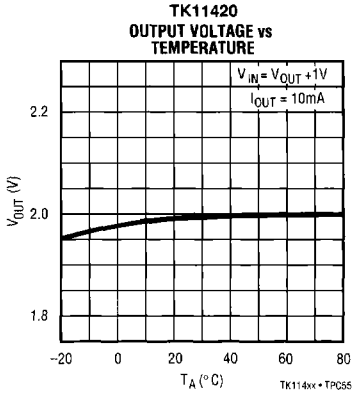
TK11460 (CONT.)



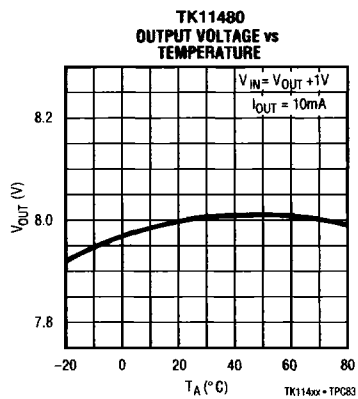
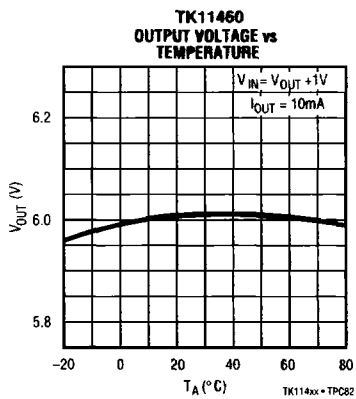
TK11480



TYPICAL PERFORMANCE CHARACTERISTICS (CONT.)

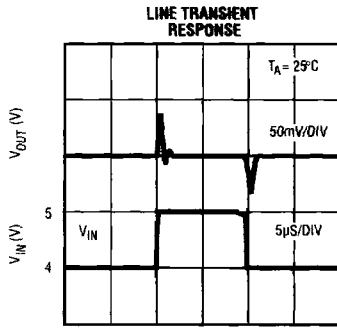


TYPICAL PERFORMANCE CHARACTERISTICS (CONT.)

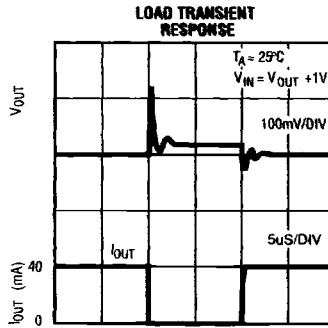


TYPICAL PERFORMANCE CHARACTERISTICS (CONT.)

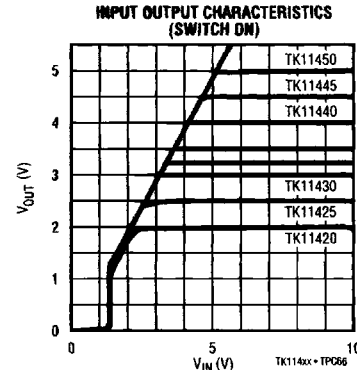
COMMON CHARACTERISTICS



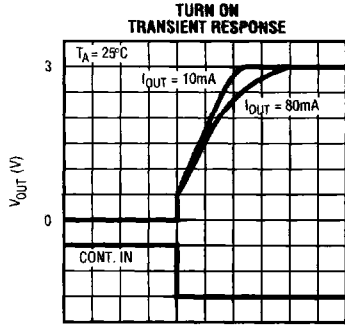
TK114xx - TPO64



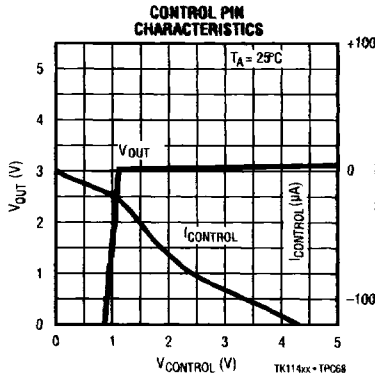
TK114xx - TPO65



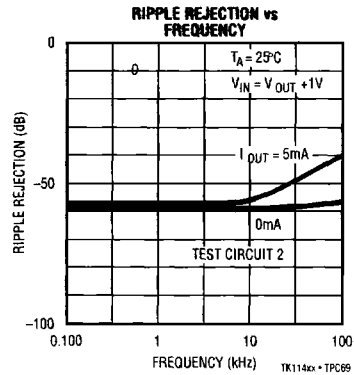
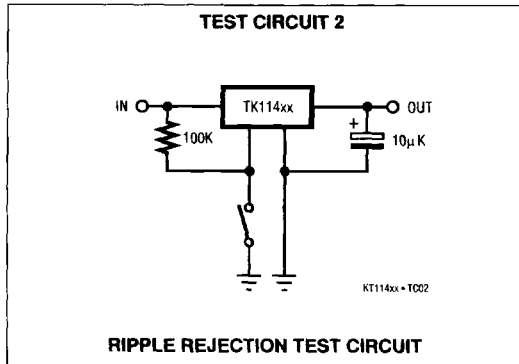
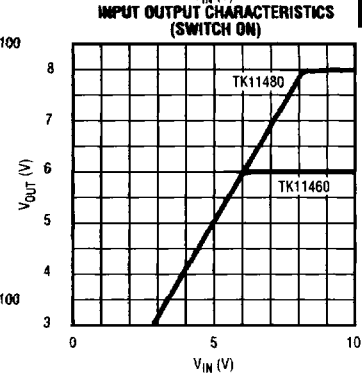
3



TK114xx - TPO67



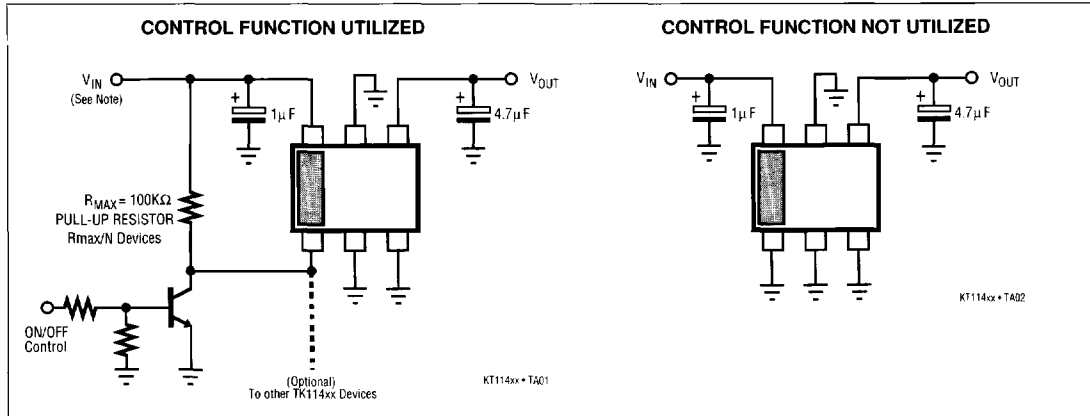
TK114xx - TPO68



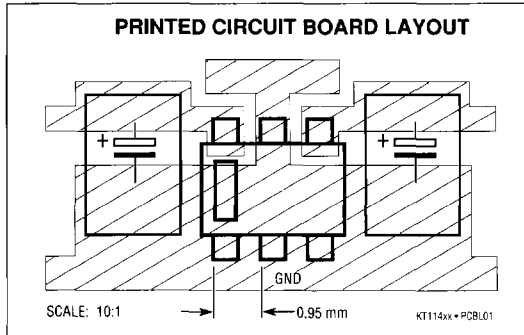
TK114xx - TPO69

TK114xx

TYPICAL APPLICATIONS



Note: Parallel connection of control pins is allowed if all devices use identical input voltage.



Application Hints

Maximize copper foil area connecting to all IC pins for optimum performance. Place input and output bypass capacitors close to the GND pin. For best transient behavior and lowest output impedance, use as large a capacitor value as possible. The temperature coefficient of the capacitance and Equivalent Series Resistance (ESR) should be taken into account. These parameters can influence power supply noise and ripple rejection. In extreme cases, oscillation may occur. In order to maintain stability, the output bypass capacitor value should be minimum 2.2 μ F for a Tantalum electrolytic or 4.7 μ F for an Aluminum electrolytic.

Handling Molded Resin Packages

All plastic molded packages absorb some moisture from the air. If moisture absorption occurs prior to soldering the device into the printed circuit board, increased separation of the lead from the plastic molding may occur, degrading the moisture barrier characteristics of the device.

This property of plastic molding compounds should not be overlooked, particularly in the case of very small packages, where the plastic is very thin.

In order to preserve the original moisture barrier properties of the package, devices are stored and shipped in moisture proof bags, filled with dry air. The bags should not be opened or damaged prior to the actual use of the devices. If this is unavoidable, the devices should be stored in a low relative humidity environment (40 to 65%) or in an enclosed environment with desiccant.